12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20260219000.1
Qualification of TI CDAT as an additional Assembly site for the Select Devices
Change Notification / Sample Request

Date: February 19, 2026
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **60** days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **60 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team
SC Business Services

20260219000.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TUSB216RWBT	NULL
TUSB216IRWBR	NULL
TUSB211AIRWBR	NULL
TUSB211ARWBR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	PCN# 20260219000.1	PCN Date:	February 19, 2026
Title:	Qualification of TI CDAT as an additional Assembly site for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	May 20, 2026	Sample requests accepted until:	April 20, 2026*

***Sample requests received after** April 20, 2026 **will not be supported.**

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Material
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the qualification of TI CDAT as an additional Assembly site for the devices listed below. Material differences between sites are as follows.

	Current	Additional
Assembly site	ATXSZ	TI CDAT
Wire diam/type	0.8mil Au	0.8mil Cu
Mold compound	SID#1800900161	4222198
MSL level	2	1

Qual details are provided in the Qual Data Section.

Reason for Change:

Supply continuity
1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties
2) Maximize flexibility within our Assembly/Test production sites.
3) Cu is easier to obtain and stock

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
ATXSZ	ASN	CHN	Suzhou
TI CDAT	**CDA**	**CHN**	**Chengdu**

Sample product shipping label (not actual product label)

Product Affected:

TUSB217ARWBR	TUSB216IRWBT	TUSB211AIRWBR
TUSB217ARWBT	TUSB216RWBR	TUSB211ARWBR
TUSB217AIRWBR	TUSB217AIRWBT	
TUSB216IRWBR	TUSB216RWBT	

Qualification Report
CDAT: X2QFN RWB Pkg Offload LBC9 Devices

Approve Date 19-August-2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TUSB217ARWBR	QBS Reference: TLV62568DBVR	QBS Reference: ADS1115IRUGR
HAST	A2	Biased HAST	130C	96 Hours	-	3/231/0	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/231/0
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/3000/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	1/22/0
ESD	E2	ESD CDM	-	1500 Volts	-	1/3/0	-
ESD	E2	ESD HBM	-	3500 Volts	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	-
CHAR	E5	Electrical Characterization	Min, Typ, Max Temp	-	-	1/30/0	-

QBS: Qual By Similarity, also known as Generic Data
Qual Device TUSB217ARWBR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2112-041

Qualification Report
CDAT: X2QFN RWB Pkg Offload A035 devices

Approve Date 7-Nov-2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TUSB320LAIRWBR	QBS Process Reference: TWL3033H3IZXX	QBS Package Reference: ADS7142IRUGR
ELFR	Early Life Failure Rate, 125C	48 Hours	-	3/4608/0	-
HTOL	Life Test, 125C	1000 Hours	-	3/231/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	3/231/0
TC	Temperature Cycle, -55/125C	700 Cycles	-	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	-	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	3/231/0	3/231/0
WBP	Bond Pull	Wires	1/30/0	-	-
WBP	Wire Pull	Wires	1/30/0	-	-
WBS	Ball Bond Shear	Wires	1/30/0	-	-

QBS: Qual By Similarity
Qual Device is qualified at LEVEL1-260C: TUSB320LAIRWBR
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green
TI Qualification ID: R-CHG-2211-006

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled “QBS Process” (for wafer fab process), “QBS Package” (for assembly process) and “QBS Product” (for product family).

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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